

Customer No.: 31561
Docket No.: 11053-US-PA
Application No.: 10/707,457

In The Claims

Claims 1-10 (cancelled).

11. (currently amended) A discrete semiconductor circuit component comprising a circuit die, said circuit die having at least one electrical contact area for connection to the packaging of said semiconductor circuit component, said at least one electrical contact area being bond to the corresponding lead of said packaging by metallic material formed by a metal ball of prescribed feed melted during the fabrication of said component.

12. (currently amended) The discrete semiconductor circuit component of claim 11, wherein said metal ball contains copper.

13. (currently amended) The discrete semiconductor circuit component of claim 11 wherein said metal ball contains aluminum.

14. (currently amended) The discrete semiconductor circuit component of claim 11, wherein said metal ball contains tin.

15. (currently amended) The discrete semiconductor circuit component of claim 11, wherein said metal ball contains lead.

16. (currently amended) The discrete semiconductor circuit component of claim 11, further comprising a second metal bump.

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17. (currently amended) The discrete semiconductor circuit component of claim 16, wherein said two metal bumps being of different sizes.

18. (currently amended) The discrete semiconductor circuit component of claim 16, wherein said two metal bumps being of different shapes.

19. (currently amended) The discrete semiconductor circuit component of claim 16, wherein said two metal bumps being made of different materials.

20. (currently amended) The semiconductor circuit component of claim 11, further comprising at least one more metal bump.